6. Assembly Information and Production Guidance

6.1 Production Guidance   Important

● The stamp hole package module produced by Mxchip must completely being patched by SMT machine in 24 hours after open firmware package. Otherwise the module should be re-package by vacuum pumping and drying before patch.

- Devices for SMT patch:

  （1）Reflow soldering machine

  （2）AOI detector

  （3）Suction nozzle with 6-8mm caliber

- Device for drying:

  （1）Cabinet type oven

  （2）Anti-static and high thermos tolerant tray

  （3）Anti-static and high thermos tolerant gloves

● Conditions of product storage (Storage environment is shown in figure 8):